

Data sheet

SAW RF filter
Base stations
TETRA

Series/type: B5073

Ordering code: B39351B5073Z810

Date: June 18, 2019

Version: 2.1

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RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

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Table of contents

4
2
5
5
6
7
8
g
10
11
13
14
15
17



RF360 Europe GmbH A Qualcomm – TDK Joint Venture

1 Application

- RF filter for TETRA receiver
- Usable band width 10 MHz

2 Features

- Package code QCC8B
- Package size 3.8±0.15 mm × 3.8±0.15 mm
- Package height 1.5+0.1/-0.15 mm
- Approximate weight 0.07 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Lead free soldering compatible with J-STD20C
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)

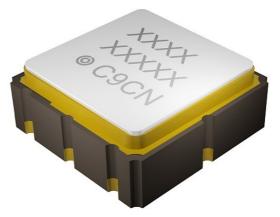
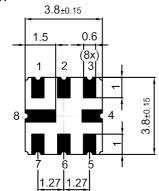


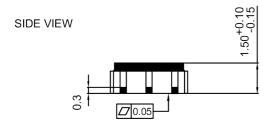
Figure 1: Picture of component with example of product marking.

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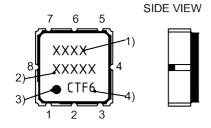
3 Package

BOTTOM VIEW





TOP VIEW



- 1)Device designation
- 2)Last five digits of the lot number
- 3)Marking for pad number 1
- 4)Example of production location and date code

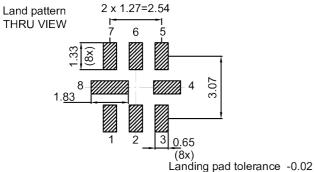


Figure 2: Drawing of package. See Sec. Package information (p. 16).

4 Pin configuration

- 1 Output (recommend or output balanced)
- 5 Input
- Ground (recommend or output balanced)
- 3, 4, 6, 7, Ground 8

5 Matching circuit

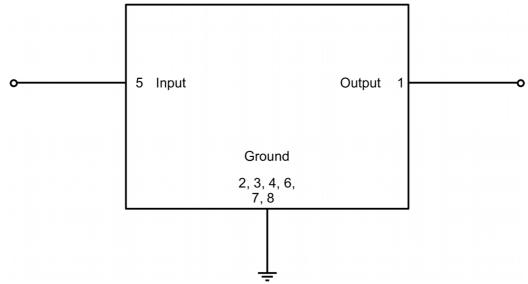


Figure 3: Schematic of matching circuit. No external matching components required.



6 Characteristics

Temperature range for specification $T_{\text{SPEC}} = -30 \,^{\circ}\text{C} \dots +70 \,^{\circ}\text{C}$

Input terminating impedance $Z_{_{\rm IN}} = 50~\Omega$ Output terminating impedance $Z_{_{\rm OUT}} = 50~\Omega$

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f _C	_	355	_	MHz
Maximum insertion attenuation			α_{max}				
	350 360	MHz		_	1.8	3.0 ¹⁾	dB
Amplitude ripple (p-p)			Δα				
	350 360	MHz		_	0.8	2.02)	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	350 360	MHz		_	1.5	2.0	
@ output port	350 360	MHz		_	1.5	2.0	
Temperature coefficient of frequency			TC_{f}	_	-36.0	_	ppm/K
Minimum attenuation			$\boldsymbol{\alpha}_{_{min}}$				
	0.1 81	MHz		27	70	_	dB
	81 82	MHz		31	65	_	dB
	82 325.8	MHz		13	60	_	dB
	325.8	MHz		27	55	_	dB
	325.8 345	MHz		10	20	_	dB
	365 390	MHz		10	20	_	dB
	390 404	MHz		6	55	_	dB
	404 421	MHz		16	55	_	dB
	421 442	MHz		27	55	_	dB
	442 512	MHz		16	50	_	dB
	512 523	MHz		41	50	_	dB
	523 781	MHz		19	47	_	dB
	781 1212	MHz		26	35	_	dB
	1212 1626	MHz		28	32	_	dB
	1626 1806	MHz		17	32	_	dB

^{1) 2.5}dB max at +15°C to +35°C.

²⁾ 1.5dB max at +15°C to +35°C.



7 Maximum ratings

Operable temperature	T _{OP} = −40 °C +125 °C	
Storage temperature	T _{STG} ¹⁾ = −40 °C +125 °C	
DC voltage	V _{DC} = 0 V	
ESD voltage	V _{ESD} ²⁾ = 100 V	Machine model.
Input power @ input port	P _{IN} = 15 dBm	Continuous wave

¹⁾ Not valid for packaging material. Please refer to definition of Shelf life (p. 15).

²⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

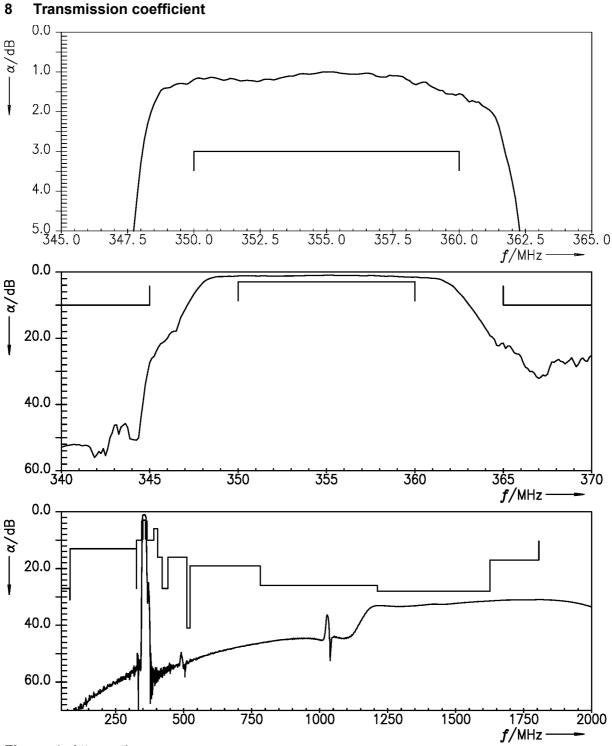
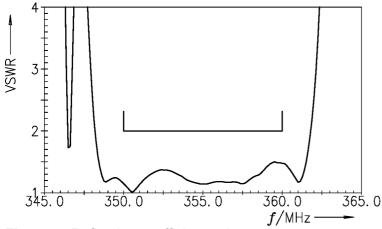


Figure 4: Attenuation.

9 Reflection coefficients



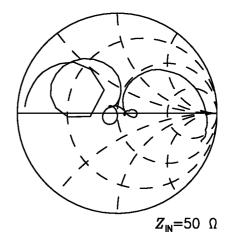
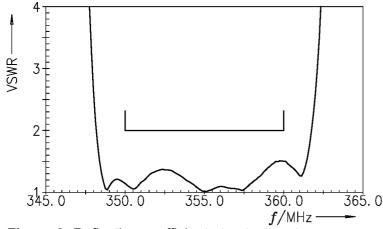


Figure 5: Reflection coefficient at input port.



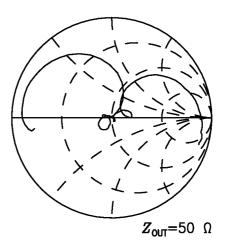


Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape

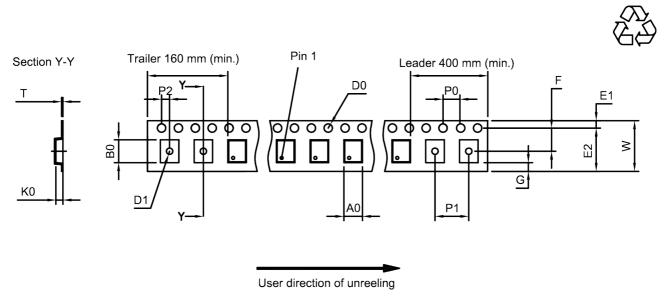


Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	4.1±0.1 mm	_	E ₂	10.25 mm (min.)	·	P ₁	8.0±0.1 mm
B ₀	4.1±0.1 mm		F	5.5±0.05 mm	_	P_2	2.0 _{±0.1} mm
D ₀	1.5+0.1/-0 mm		G	0.75 mm (min.)		Т	0.3±0.05 mm
D ₁	1.5 mm (min.)		\mathbf{K}_0	1.8±0.1 mm	_	W	12.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	_	P ₀	4.0±0.1 mm	_		

Table 1: Tape dimensions.

10.2 Reel with diameter of 330 mm

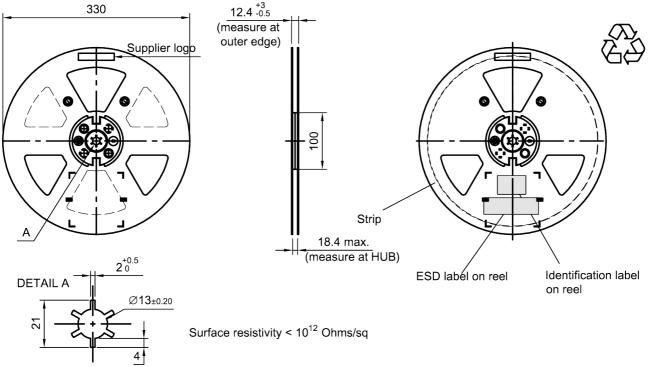


Figure 8: Drawing of reel (first-angle projection) with diameter of 330 mm.

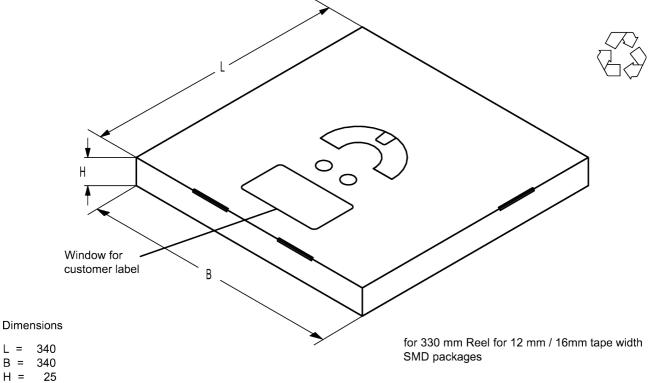


Figure 9: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

■ Device designation: The 4-character device designation of the ordering code is used for the marking.

Example for 4-character device designation: B3xxxxB1234xxxx

■ Lot number: The last 5 digits of the lot number are used for the marking.

Example: <u>12345</u>

■ Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

1 st digit (day)						2 nd digit (year)			3 rd digit (month)				
Day	Code	Day	Code	Day	Code	Year	Code	Year	Code	Month	Code	Month	Code
1	1	11	Α	21	М	2010	Α	2022	Р	Jan	1	Jul	7
2	2	12	В	22	N	2011	В	2023	R	Feb	2	Aug	8
3	3	13	С	23	Р	2012	С	2024	S	Mar	3	Sep	9
4	4	14	D	24	R	2013	D	2025	Т	Apr	4	Oct	0
5	5	15	E	25	S	2014	Е	2026	U	May	5	Nov	N
6	6	16	F	26	Т	2015	F	2027	V	Jun	6	Dec	D
7	7	17	Н	27	U	2016	Н	2028	W				
8	8	18	J	28	V	2017	J	2029	Х				
9	9	19	K	29	W	2018	K	2030	Z				
10	0	20	L	30	Х	2019	L	2031	Α				
				31	Z	2020	М	2032	В				
						2021	N	and	so on				

Table 2: Production date code.

Example of how to decode production location and date code:

Code: CTF6

Location: C \rightarrow Wuxi

Day: T \rightarrow 26th

Year: F \rightarrow 2015

Month: 6 \rightarrow June

12 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature <i>T</i>	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

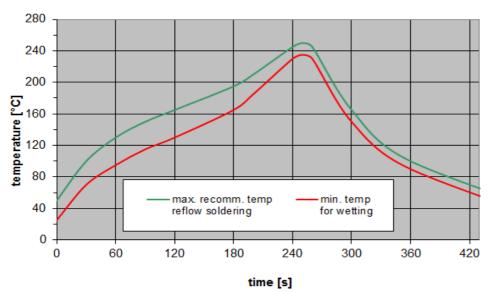


Figure 10: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Shelf life

The shelf life of components is determined by solderability of the package terminals. It is specified as 2 years from manufacturing date assuming the following conditions:

- storage in original packaging and non-aggressive atmosphere,
- storage temperature ranging from -25 °C to +40 °C, and
- storage humidity with ≤ 75 % r.h. mean annual humidity, ≤ 95 % r.h. for max. 30 days / year, and no dew condensation.



14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

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14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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- 3. The warnings, cautions and product-specific notes must be observed.
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